# RENESAS Low Skew, 1-to-18 LVPECL-TO-LVCMOS / LVTTL Fanout Buffer

DATASHEET

## GENERAL DESCRIPTION

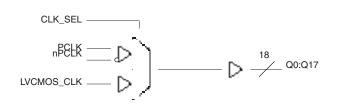
The ICS83940-01 is a low skew, 1-to-18 LVPECL-to-LVCMOS/LVTTL Fanout Buffer. The ICS83940-01 has two selectable clock inputs. The PCLK, nPCLK pair can accept LVPECL, CML or SSTL input levels. The single ended clock input accepts LVCMOS or LVTTL input levels. The low impedance LVCMOS/LVTTL outputs are designed to drive  $50\Omega$  series or parallel terminated transmission lines. The effective fanout can be increased from 18 to 36 by utilizing the ability of the outputs to drive two series terminated lines.

The ICS83940-01 is characterized at full 3.3V, full 2.5V and mixed 3.3V input and 2.5V output operating supply modes. Guaranteed output and part-to-part skew characteristics make the ICS83940-01 ideal for those clock distribution applications demanding well defined performance and repeatability.

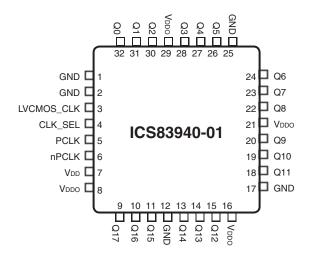
### **F**EATURES

- Eighteen LVCMOS/LVTTL outputs, 23Ω typical output impedance
- Selectable LVCMOS\_CLK or LVPECL clock inputs
- LVCMOS\_CLK supports the following input types: LVCMOS or LVTTL
- PCLK, nPCLK supports the following input types: LVPECL, CML, SSTL
- Maximum output frequency: 250MHz
- Output skew: 85ps (maximum)
- Part-to-part skew: 750ps (maximum)
- Full 3.3V, 2.5V or mixed 3.3V, 2.5V supply modes
- 0°C to 70°C ambient operating temperature
- Available in lead-free RoHS compliant package

# **BLOCK DIAGRAM**



# PIN ASSIGNMENT



32-Lead LQFP Y Pacakge 7mm x 7mm x 1.4mm package body Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Т	уре	Description
1, 2, 12, 17, 25	GND	Power		Power supply ground.
3	LVCMOS_CLK	Input	Pulldown	Clock input. LVCMOS / LVTTL interface levels.
4	CLK_SEL	Input	Pulldown	Clock select input. Selects LVCMOS / LVTTL clock input when HIGH. Selects PCLK, nPCLK inputs when LOW. LVCMOS / LVTTL interface levels.
5	PCLK	Input	Pulldown	Non-inverting differential LVPECL clock input.
6	nPCLK	Input		Inverting differential LVPECL clock input.  V <sub>DD</sub> /2 default when left floating.
7	$V_{_{ m DD}}$	Power		Power supply pin.
8, 16, 21, 29	$V_{ m DDO}$	Power		Output supply pins.
9, 10, 11, 13, 14, 15, 18, 19, 20, 22, 23, 24, 26, 27, 28, 30, 31, 32	Q17, Q16, Q15, Q14, Q13, Q12, Q11, Q10, Q9, Q8, Q7, Q6, Q5, Q4, Q3, Q2, Q1, Q0	Output		Clock outputs. LVCMOS / LVTTL interface levels.

NOTE: Pulldown refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C <sub>PD</sub>	Power Dissipation Capacitance (per output)			6		pF
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ
R <sub>OUT</sub>	Output Impedance		18		28	Ω

TABLE 3A. CLOCK SELECT FUNCTION TABLE

Control Input	Clock				
CLK_SEL	PCLK, nPCLK	LVCMOS_CLK			
0	Selected	De-selected			
1	De-selected	Selected			

TABLE 3B. CLOCK INPUT FUNCTION TABLE

	Inj	outs		Outputs	Input to Output Made	Delevity
CLK_SEL	LVCMOS_CLK	PCLK	nPCLK	Q0:Q17	Input to Output Mode	Polarity
0	_	0	1	LOW	Differential to Single Ended	Non Inverting
0	_	1	0	HIGH	Differential to Single Ended	Non Inverting
0	_	0	Biased; NOTE 1	LOW	Single Ended to Single Ended	Non Inverting
0	_	1	Biased; NOTE 1	HIGH	Single Ended to Single Ended	Non Inverting
0	_	Biased; NOTE 1	0	HIGH	Single Ended to Single Ended	Inverting
0	_	Biased; NOTE 1	1	LOW	Single Ended to Single Ended	Inverting
1	0	_	_	LOW	Single Ended to Single Ended	Non Inverting
1	1	_	_	HIGH	Single Ended to Single Ended	Non Inverting

NOTE 1: Please refer to the Application Information section, "Wiring the Differential Input to Accept Single Ended Levels".



#### **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, V<sub>DD</sub> 3.6V

Inputs,  $V_{I}$  -0.3V to  $V_{DD}$  + 0.3V

Outputs,  $V_O$  -0.3V to  $V_{DDO}$  + 0.3V

Input Current, I<sub>IN</sub> ±20mA

Storage Temperature, T<sub>STG</sub> -40°C to 125°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. DC Characteristics,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%, T_A = 0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	LVCMOS_CLK		2.4		V <sub>DD</sub>	V
V <sub>IL</sub>	Input Low Voltage	LVCMOS_CLK				0.8	V
V <sub>PP</sub>	Peak-to-Peak Input Voltage	PCLK, nPCLK		500		1000	mV
V <sub>CMR</sub>	Input Common Mode Voltage; NOTE 1, 2	PCLK, nPCLK		V <sub>DD</sub> - 1.4		V <sub>DD</sub> - 0.6	V
I <sub>IN</sub>	Input Current					±200	μΑ
V <sub>OH</sub>	Output High Voltage		I <sub>OH</sub> = -20mA	2.4			V
V <sub>OL</sub>	Output Low Voltage		I <sub>OL</sub> = 20mA			0.5	V
I <sub>DD</sub>	Power Supply Current					25	mA

NOTE 1: For single ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{\rm DD}$  + 0.3V.

NOTE 2: Common mode voltage is defined as  $V_{_{\rm IH}}$ .

Table 4B. DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 2.5V \pm 5\%$ , Ta =  $0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	LVCMOS_CLK		2.4		V <sub>DD</sub>	V
V <sub>IL</sub>	Input Low Voltage	LVCMOS_CLK				0.8	V
V <sub>PP</sub>	Peak-to-Peak Input Voltage	PCLK, nPCLK		300		1000	mV
V <sub>CMR</sub>	Input Common Mode Voltage; NOTE 1, 2	PCLK, nPCLK		V <sub>DD</sub> - 1.4		V <sub>DD</sub> - 0.6	٧
I <sub>IN</sub>	Input Current					±200	μΑ
V <sub>OH</sub>	Output High Voltage		I <sub>OH</sub> = -20mA	1.8			V
V <sub>OL</sub>	Output Low Voltage		I <sub>OL</sub> = 20mA			0.5	V
I <sub>DD</sub>	Power Supply Current					25	mA

NOTE 1: For single ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{\rm np}$  + 0.3V.

NOTE 2: Common mode voltage is defined as  $V_{_{\rm IH}}$ .



Table 4C. DC Characteristics,  $V_{DD} = V_{DDO} = 2.5 V \pm 5\%$ , Ta =  $0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	LVCMOS_CLK		2		V <sub>DD</sub>	V
V <sub>IL</sub>	Input Low Voltage	LVCMOS_CLK				0.8	V
V <sub>PP</sub>	Peak-to-Peak Input Voltage	PCLK, nPCLK		300		1000	mV
V <sub>CMR</sub>	Input Common Mode Voltage; NOTE 1, 2	PCLK, nPCLK		V <sub>DD</sub> - 1.4		V <sub>DD</sub> - 0.6	V
I <sub>IN</sub>	Input Current					±200	μA
V <sub>OH</sub>	Output High Voltage		I <sub>OH</sub> = -12mA	1.8			V
V <sub>OL</sub>	Output Low Voltage		I <sub>OL</sub> = 12mA			0.5	V
I <sub>DD</sub>	Power Supply Current					25	mA

NOTE 1: For single ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{\rm pp}$  + 0.3V.

NOTE 2: Common mode voltage is defined as  $V_{_{\rm IH}}$ .

Table 5A. AC Characteristics,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ , Ta =  $0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					250	MHz
	Dranagation Dalay	PCLK, nPCLK; NOTE 1, 5	f 150MHz	1.6		3.0	ns
t <sub>pLH</sub>	Propagation Delay	LVCMOS_CLK; NOTE 2, 5	f 150MHz	1.8		3.0	ns
	Dranagation Dalay	PCLK, nPCLK; NOTE 1, 5	f > 150MHz	1.6		3.3	ns
t <sub>pLH</sub>	Propagation Delay	LVCMOS_CLK; NOTE 2, 5	f > 150MHz	1.8		3.2	ns
tok(o)	Output Skew;	PCLK, nPCLK	Measured on			85	ps
tsk(o)	NOTE 3, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			85	ps
tal(/pp)	Part-to-Part Skew;	PCLK, nPCLK	f 150MHz			1.4	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f 150MHz			1.2	ns
+=1:/:=:=\	Part-to-Part Skew;	PCLK, nPCLK	f > 150MHz			1.7	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f > 150MHz			1.4	ns
tal(/pp)	Part-to-Part Skew;	PCLK, nPCLK	Measured on			850	ps
tsk(pp)	NOTE 4, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			750	ps
t <sub>R</sub> , t <sub>F</sub>	Output Rise/Fall Time		20% to 80%	400		800	ps
odc	Output Duty Cycle		f 150MHz	45		55	%
ouc	Output Daty Cycle		150MHz < f 250MHz	40		60	%

All parameters measured at 200MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output V<sub>ppo</sub>/2.

NOTE 2: Measured from  $V_{DD}/2$  to  $V_{DDO}/2$ .

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V<sub>DDQ</sub>/2.

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages, same temperature,

and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V<sub>ppo</sub>/2.

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{\rm DDO}/2$ .



Table 5B. AC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 2.5V \pm 5\%$ , Ta =  $0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					250	MHz
+	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	f 150MHz	1.7		3.2	ns
t <sub>pLH</sub>	Fropagation Delay	LVCMOS_CLK; NOTE 2, 5	f 150MHz	1.7		3.0	ns
+	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	f > 150MHz	1.6		3.4	ns
t <sub>pLH</sub>	Fropagation Delay	LVCMOS_CLK; NOTE 2, 5	f > 150MHz	1.8		3.3	ns
tsk(o)	Output Skew;	PCLK, nPCLK	Measured on			150	ps
isk(0)	NOTE 3, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			150	ps
tol(nn)	Part-to-Part Skew;	PCLK, nPCLK	f 150MHz			1.5	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f 150MHz			1.3	ns
+=1:/:=:=\	Part-to-Part Skew;	PCLK, nPCLK	f > 150MHz			1.8	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f > 150MHz			1.5	ns
4-1-()	Part-to-Part Skew;	PCLK, nPCLK	Measured on			850	ps
tsk(pp)	NOTE 4, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			750	ps
t <sub>R</sub> , t <sub>F</sub>	Output Rise/Fall Tim	ne	20% to 80%	400		800	ps
odc	Output Duty Cycle		f < 134MHz	45		55	%
ouc	Output Duty Cycle		134MHz f < 250MHz	40		60	%

All parameters measured at 200MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output V<sub>ppo</sub>/2.

NOTE 2: Measured from  $V_{DD}/2$  to  $V_{DDO}/2$ . NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at  $V_{DDO}/2$ .

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages, same temperature, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V<sub>DDO</sub>/2.

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{ppo}/2$ .



Table 5C. AC Characteristics,  $V_{DD} = V_{DDO} = 2.5V \pm 5\%$ , Ta =  $0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					200	MHz
	Propagation Delay;	PCLK, nPCLK; NOTE 1, 5	f 150MHz	1.2		3.8	ns
t <sub>pLH</sub>	Fropagation Delay,	LVCMOS_CLK; NOTE 2, 5	f 150MHz	1.5		3.2	ns
	Propagation Delay;	PCLK, nPCLK; NOTE 1, 5	f > 150MHz	1.5		3.7	ns
t <sub>pLH</sub>	Propagation Delay,	LVCMOS_CLK; NOTE 2, 5	f > 150MHz	2		3.6	ns
tsk(o)	Output Skew;	PCLK, nPCLK	Measured on			150	ps
isk(0)	NOTE 3, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			150	ps
tol(nn)	Part-to-Part Skew;	PCLK, nPCLK	f 150MHz			2.6	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f 150MHz			1.7	ns
4-1-()	Part-to-Part Skew;	PCLK, nPCLK	f > 150MHz			2.2	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f > 150MHz			1.7	ns
tok/nn)	Part-to-Part Skew;	PCLK, nPCLK	Measured on			1.2	ns
tsk(pp)	NOTE 4, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			1.0	ns
t <sub>R</sub> , t <sub>F</sub>	Output Rise/Fall Tim	е	20% to 80%	400		800	ps
odc	Output Duty Cycle		f < 134MHz	45		55	%
			134MHz f 200MHz	40		60	%

All parameters measured at 200MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output  $V_{\rm DDO}/2$ .

NOTE 2: Measured from  $V_{\rm DD}/2$  to  $V_{\rm DDO}/2$ .

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at  $V_{\rm DDO}/2$ .

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages, same temperature, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{ppq}/2$ .

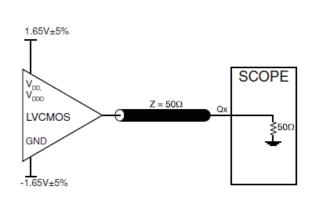
NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

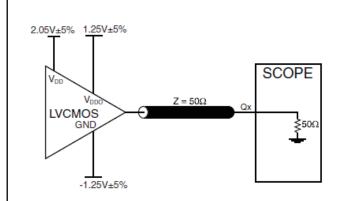
NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges,

and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V<sub>DDQ</sub>/2.



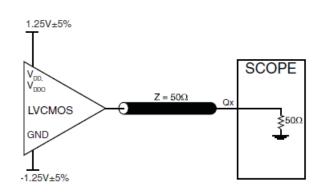
# PARAMETER MEASUREMENT INFORMATION

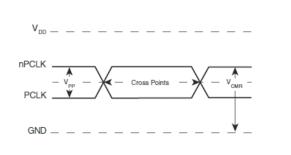




#### 3.3V OUTPUT LOAD AC TEST CIRCUIT

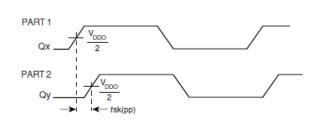
# 3.3V/2.5V OUTPUT LOAD AC TEST CIRCUIT

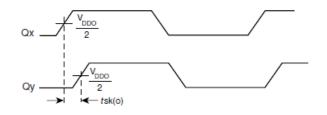




# 2.5V OUTPUT LOAD AC TEST CIRCUIT

# DIFFERENTIAL INPUT LEVEL

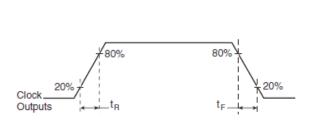


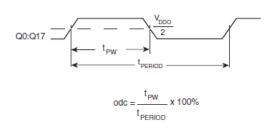


#### PART-TO-PART SKEW

**OUTPUT SKEW** 

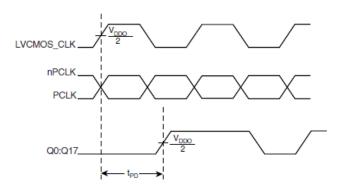






## OUTPUT RISE/FALL TIME

## OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD



#### PROPAGATION DELAY

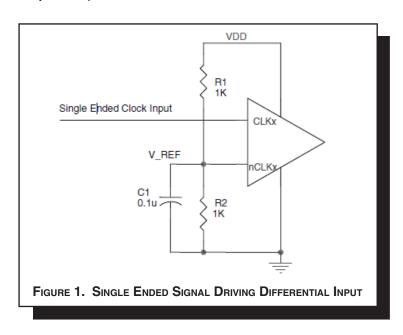


# **APPLICATION INFORMATION**

#### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_REF = V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the  $V_REF$ 

in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{\rm DD}\!=\!3.3$ V, V\_REF should be 1.25V and R2/R1 = 0.609.



#### RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

#### INPUTS: OUTPUTS:

#### **CLK INPUT:**

For applications not requiring the use of a clock input, it can be left floating. Though not required, but for additional protection, a  $1k\Omega$  resistor can be tied from the CLK input to ground.

#### PCLK/nPCLK INPUT:

For applications not requiring the use of a differential input, both the PCLK and nPCLK pins can be left floating. Though not required, but for additional protection, a  $1k\Omega$  resistor can be tied from PCLK to ground.

#### LVCMOS CONTROL PINS:

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A  $1k\Omega$  resistor can be used.

LVCMOS OUTPUT:

All unused LVCMOS output can be left floating. We recommend that there is no trace attached.



#### LVPECL CLOCK INPUT INTERFACE

The PCLK /nPCLK accepts LVPECL, CML, SSTL and other differential signals. Both Vswing and Voh must meet the VPP and VcmR input requirements. *Figures 2A to 2E* show interface examples for the PCLK/nPCLK input driven by the most common driver types. The input interfaces

suggested here are examples only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.

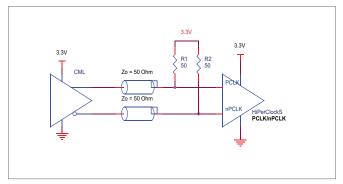


FIGURE 2A. PCLK/nPCLK INPUT DRIVEN
BY AN OPEN COLLECTOR CML DRIVER

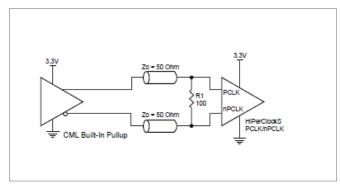


FIGURE 2B. PCLK/nPCLK INPUT DRIVEN
BY A BUILT-IN PULLUP CML DRIVER

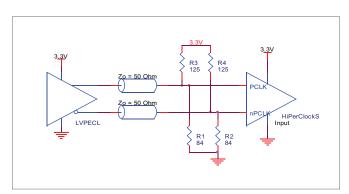


FIGURE 2C. PCLK/nPCLK INPUT DRIVEN
BY A 3.3V LVPECL DRIVER

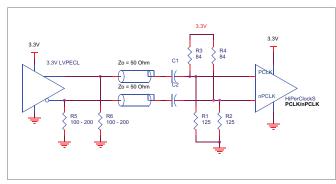


FIGURE 2D. PCLK/nPCLK INPUT DRIVEN
BY A 3.3V LVPECL DRIVER WITH AC COUPLE

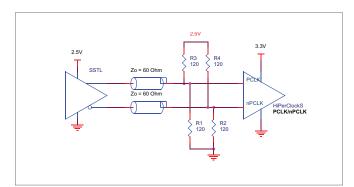


FIGURE 2E. PCLK/nPCLK INPUT DRIVEN BY AN SSTL DRIVER

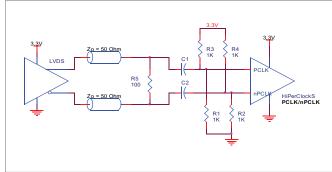


FIGURE 2F. PCLK/nPCLK INPUT DRIVEN
BY A 3.3V LVDS DRIVER



# **RELIABILITY INFORMATION**

# Table 6. $\theta_{\text{JA}} \text{vs. Air Flow Table for 32 Lead LQFP}$

# $\theta_{\text{JA}}$ by Velocity (Linear Feet per Minute)

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

#### TRANSISTOR COUNT

The transistor count for ICS83940-01 is: 819



PACKAGE OUTLINE - Y SUFFIX FOR 32 LEAD LQFP

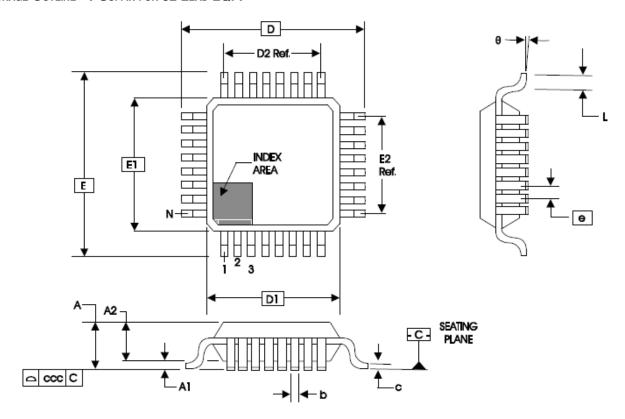


TABLE 7. PACKAGE DIMENSIONS

	JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS						
SYMBOL	BBA						
STWIBOL	MINIMUM	MINIMUM NOMINAL					
N		32					
Α			1.60				
A1	0.05		0.15				
A2	1.35	1.40	1.45				
b	0.30	0.37	0.45				
С	0.09	0.09 0.20					
D		9.00 BASIC					
D1		7.00 BASIC					
D2		5.60 Ref.					
E		9.00 BASIC					
E1		7.00 BASIC					
E2		5.60 Ref.					
е		0.80 BASIC					
L	0.45 0.60 0.75						
θ	0°		<b>7</b> °				
ccc			0.10				

Reference Document: JEDEC Publication 95, MS-026



## Table 8. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
83940DY-01LF	ICS83940D01L	32 Lead "Lead-Free" LQFP	tray	0°C to 70°C
83940DY-01LFT	ICS83940D01L	32 Lead "Lead-Free" LQFP	reel	0°C to 70°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS complaint.



REVISION HISTORY SHEET					
Rev	Table	Page	Description of Change		
А	Т8	1 9 10 13	Added Lead-Free bullet. Added Recommendations for Unused Input and Output Pins. Updated LVPECL Clock Input Interface section. Added Lead-Free part number, marking and note.	11/18/05	
A	Т8	13 15	Updated datasheet's header/footer with IDT from ICS. Removed ICS prefix from Part/Order Number column. Added Contact Page.	8/4/10	
А	Т	13	Removed Leaded devices Updated Datasheet format	11/4/14	



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